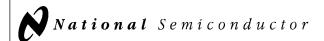
# 54F32,74F32

54F32 Quad 2-Input OR Gate



Literature Number: SNOS186A



## 54F/74F32 Quad 2-Input OR Gate

### **General Description**

## **Features**

This device contains four independent gates, each of which performs the logic OR function.

■ Guaranteed 4000V minimum ESD protection

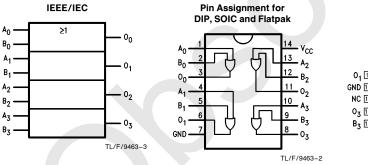
Commercial	Military	Package Number	Package Description	
74F32PC		N14A	14-Lead (0.300" Wide) Molded Dual-In-Line	
	54F32DM (Note 2)	J14A	14-Lead Ceramic Dual-In-Line	
74F32SC (Note 1)		M14A	14-Lead (0.150" Wide) Molded Small Outline, JEDEC	
74F32SJ (Note 1)		M14D	14-Lead (0.300" Wide) Molded Small Outline, EIAJ	
	54F32FM (Note 2)	W14B	14-Lead Cerpack	
	54F32LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C	

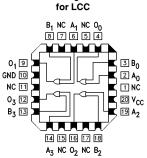
Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

## **Logic Symbol**

## **Connection Diagrams**





Pin Assignment

TI /F/9463-1

## Unit Loading/Fan Out

		54F/74F				
Pin Names	Description	U.L. HIGH/LOW	Input I <sub>IH</sub> /I <sub>IL</sub> Output I <sub>OH</sub> /I <sub>OL</sub>			
A <sub>n</sub> , B <sub>n</sub> O <sub>n</sub>	Inputs Outputs	1.0/1.0 50/33.3	20 μA/ – 0.6 mA – 1 mA/20 mA			

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#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{lll} \mbox{Storage Temperature} & -65^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \mbox{Ambient Temperature under Bias} & -55^{\circ}\mbox{C to} + 125^{\circ}\mbox{C} \\ \mbox{Junction Temperature under Bias} & -55^{\circ}\mbox{C to} + 175^{\circ}\mbox{C} \\ \mbox{Plastic} & -55^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \end{array}$ 

V<sub>CC</sub> Pin Potential to

Voltage Applied to Output

in HIGH State (with  $V_{CC} = 0V$ )

 $\begin{array}{ll} \mbox{Standard Output} & -0.5\mbox{V to V}_{CC} \\ \mbox{TRI-STATE} \mbox{$^{\circ}$ Output} & -0.5\mbox{V to } +5.5\mbox{V} \end{array}$ 

Current Applied to Output in LOW State (Max) twice the rated I<sub>OL</sub> (mA) ESD Last Passing Voltage (Min) 4000V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

# Recommended Operating Conditions

Free Air Ambient Temperature

 $\begin{array}{ll} \mbox{Military} & -55\mbox{°C to} + 125\mbox{°C} \\ \mbox{Commercial} & \mbox{0°C to} + 70\mbox{°C} \\ \end{array}$ 

Supply Voltage

Military +4.5V to +5.5V Commercial +4.5V to +5.5V

#### **DC Electrical Characteristics**

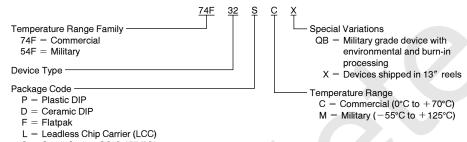
Symbol	Parameter		54F/74F			Units	V <sub>CC</sub>	Conditions	
			Min	Тур	Max	Oilles	VCC	Conditions	
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal		
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal		
V <sub>CD</sub>	Input Clamp Diode Vo			-1.2	V	Min	$I_{\text{IN}} = -18 \text{ mA}$		
V <sub>OH</sub>	Output HIGH Voltage	54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 5% V <sub>CC</sub>	2.5 2.5 2.7			V	Min	$I_{OH} = -1 \text{ mA}$ $I_{OH} = -1 \text{ mA}$ $I_{OH} = -1 \text{ mA}$	
V <sub>OL</sub>	Output LOW Voltage	54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub>			0.5 0.5	٧	Min	$I_{OL} = 20 \text{ mA}$ $I_{OL} = 20 \text{ mA}$	
I <sub>IH</sub>	Input HIGH Current	54F 74F			20.0 5.0	μΑ	Max	$V_{IN} = 2.7V$	
I <sub>BVI</sub>	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μΑ	Max	V <sub>IN</sub> = 7.0V	
I <sub>CEX</sub>	Output HIGH Leakage Current	54F 74F			250 50	μΑ	Max	V <sub>OUT</sub> = V <sub>CC</sub>	
V <sub>ID</sub>	Input Leakage Test	74F	4.75			٧	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded	
lod	Output Leakage Circuit Current	74F			3.75	μΑ	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded	
I <sub>IL</sub>	Input LOW Current				-0.6	mA	Max	V <sub>IN</sub> = 0.5V	
los	Output Short-Circuit Current		-60		-150	mA	Max	V <sub>OUT</sub> = 0V	
Icch	Power Supply Current			6.1	9.2	mA	Max	V <sub>O</sub> = HIGH	
ICCL	Power Supply Current			10.3	15.5	mA	Max	V <sub>O</sub> = LOW	

## **AC Electrical Characteristics**

	Parameter	74F			54F		74F		Units
Symbol		$egin{array}{ll} T_{A}=&+25^{\circ}C \ V_{CC}=&+5.0V \ C_{L}=&50\ pF \end{array}$			$ extsf{T}_{ extsf{A}},  extsf{V}_{ extsf{CC}} =  extsf{Mil} \  extsf{C}_{ extsf{L}} =  extsf{50 pF}$		extstyle  ext		
		Min	Тур	Max	Min	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay	3.0	4.2	5.6	3.0	7.5	3.0	6.6	ns
t <sub>PHL</sub>	A <sub>n</sub> , B <sub>n</sub> to O <sub>n</sub>	3.0	4.0	5.3	2.5	7.5	3.0	6.3	115

## **Ordering Information**

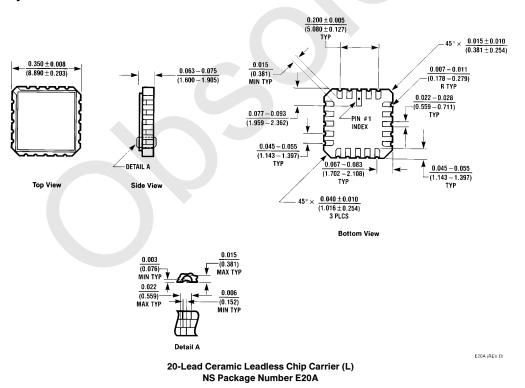
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

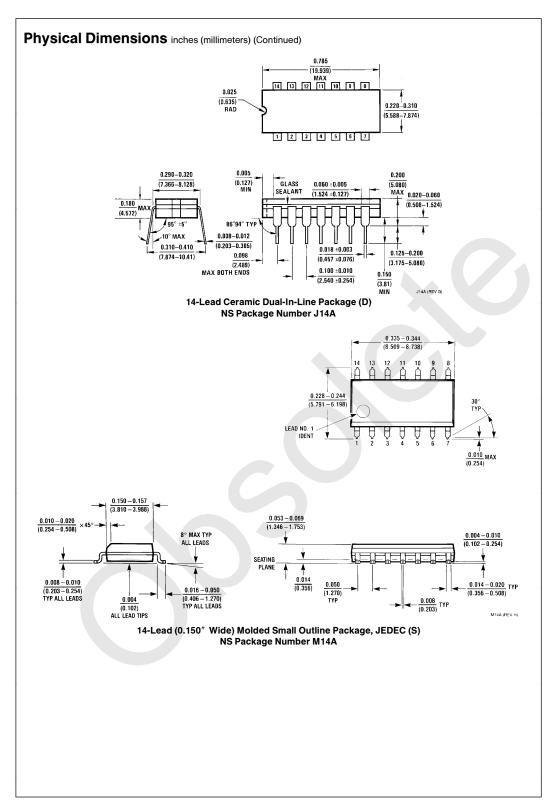


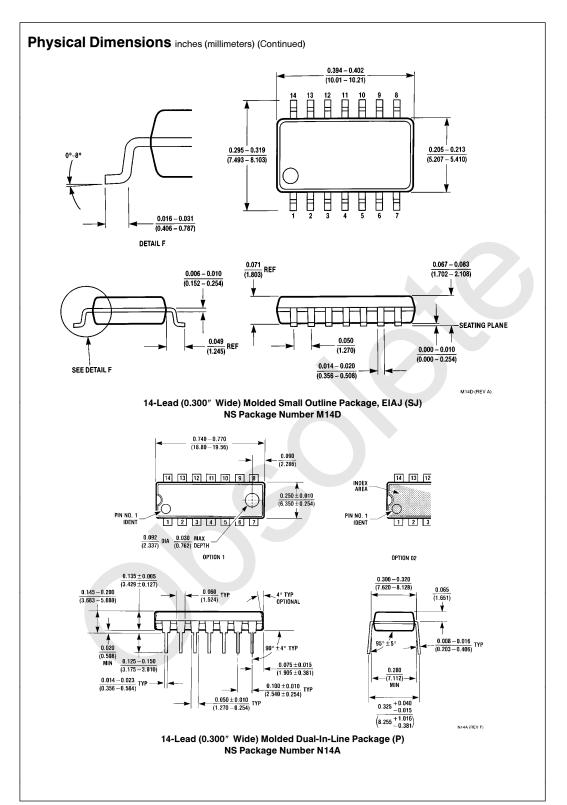
S = Small Outline SOIC JEDEC

SJ = Small Outline SOIC EIAJ

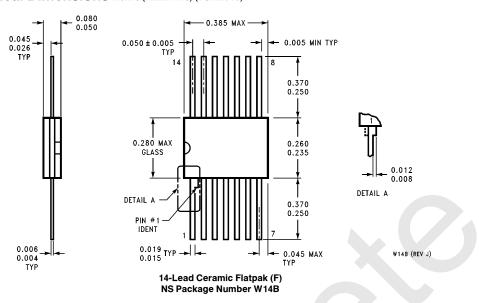
#### Physical Dimensions inches (millimeters)







### Physical Dimensions inches (millimeters) (Continued)



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